

A B S T R A C T

"IC Testing Apparatus and Method"

Main tester unit tests an IC device for presence of a defect for each addresses of the IC device under predetermined
5 test conditions and stores test results for the individual addresses into a first memory. Curing analysis processing section cures each of the addresses of the IC device determined as defective, on the basis of the test results for the individual addresses stored in the first memory, so as to
10 replace a physical space of the defective addresses with an extra address space. In parallel with the operations by the curing analysis processing section, a defect analysis section acquires, from the main tester unit, the test results for the individual addresses along with data indicative of the
15 predetermined test conditions for storage into a second memory, and analyzes a specific cause of the defect in the IC device on the basis of the stored data in the second memory.

(Figure 1)